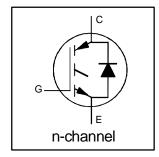
# International Rectifier

# IRGPH30MD2

INSULATED GATE BIPOLAR TRANSISTOR WITH ULTRAFAST SOFT RECOVERY DIODE

#### **Features**

- Short circuit rated -10µs @125°C, V GF = 15V
- Switching-loss rating includes all "tail" losses
- HEXFRED<sup>™</sup> soft ultrafast diodes
- Optimized for medium operating frequency (1 to 10kHz)



Short Circuit Rated Fast CoPack IGBT

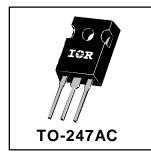
 $V_{CES} = 1200V$   $V_{CE(sat)} \le 3.5V$ 

 $@V_{GE} = 15V, I_C = 9.0A$ 

#### **Description**

Co-packaged IGBTs are a natural extension of International Rectifier's well known IGBT line. They provide the convenience of an IGBT and an ultrafast recovery diode in one package, resulting in substantial benefits to a host of high-voltage, high-current, applications.

These new short circuit rated devices are especially suited for motor control and other applications requiring short circuit withstand capability.



**Absolute Maximum Ratings** 

	Parameter	Max.	Units
V <sub>CES</sub>	Collector-to-Emitter Voltage	1200	V
I <sub>C</sub> @ T <sub>C</sub> = 25°C	Continuous Collector Current	15	
I <sub>C</sub> @ T <sub>C</sub> = 100°C	Continuous Collector Current	9.0	
I <sub>CM</sub>	Pulsed Collector Current ①	30	Α
I <sub>LM</sub>	Clamped Inductive Load Current ②	30	
I <sub>F</sub> @ T <sub>C</sub> = 100°C	Diode Continuous Forward Current	6.0	
I <sub>FM</sub>	Diode Maximum Forward Current	30	
t <sub>sc</sub>	Short Circuit Withstand Time	10	μs
$V_{GE}$	Gate-to-Emitter Voltage	± 20	V
$P_D @ T_C = 25^{\circ}C$	Maximum Power Dissipation	100	W
P <sub>D</sub> @ T <sub>C</sub> = 100°C	Maximum Power Dissipation	42	
TJ	Operating Junction and	-55 to +150	
T <sub>STG</sub>	Storage Temperature Range		°C
	Soldering Temperature, for 10 sec.	300 (0.063 in. (1.6mm) from case)	
	Mounting Torque, 6-32 or M3 Screw.	10 lbf•in (1.1 N•m)	

#### **Thermal Resistance**

	Parameter	Min.	Тур.	Max.	Units
$R_{\theta JC}$	Junction-to-Case - IGBT	_	_	1.2	
$R_{\theta JC}$	Junction-to-Case - Diode	_	_	2.5	°C/W
$R_{\theta CS}$	Case-to-Sink, flat, greased surface	_	0.24	_	
$R_{\theta JA}$	Junction-to-Ambient, typical socket mount	_	_	40	
Wt	Weight	_	6 (0.21)	_	g (oz)

### Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise specified)

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	Parameter	Min.	Тур.	Max.	Units	Conditions	
V <sub>(BR)CES</sub>	Collector-to-Emitter Breakdown Voltage 3	1200	_	_	V	V <sub>GE</sub> = 0V, I <sub>C</sub> = 250μA	
$\Delta V_{(BR)CES}/\Delta T_J$	Temperature Coeff. of Breakdown Voltage	_	_	_	V/°C	V <sub>GE</sub> = 0V, I <sub>C</sub> = 1.0mA	
V <sub>CE(on)</sub>	Collector-to-Emitter Saturation Voltage	_	3.1	3.5		$I_C = 9.0A$ $V_{GE} = 15V$	
		_	4.9	_	V	I <sub>C</sub> = 15A	
		_	3.6	_		I <sub>C</sub> = 9.0A, T <sub>J</sub> = 150°C	
$V_{GE(th)}$	Gate Threshold Voltage	3.0	_	5.5		$V_{CE} = V_{GE}$ , $I_C = 250\mu A$	
$\Delta V_{GE(th)}/\Delta T_J$	Temperature Coeff. of Threshold Voltage	_	-14	_	mV/°C	$V_{CE} = V_{GE}, I_{C} = 250 \mu A$	
g <sub>fe</sub>	Forward Transconductance ④	2.5	_	_	S	$V_{CE} = 100V, I_{C} = 9.0A$	
I <sub>CES</sub>	Zero Gate Voltage Collector Current	_		250	μΑ	$V_{GE} = 0V, V_{CE} = 1200V$	
		_		2500		$V_{GE} = 0V, V_{CE} = 1200V, T_{J} = 150^{\circ}C$	
$V_{\text{FM}}$	Diode Forward Voltage Drop	_	2.7	3.0	V	$I_{C} = 6.0A$	
		_	2.4	2.7		$I_C = 6.0A$ , $T_J = 150$ °C	
I <sub>GES</sub>	Gate-to-Emitter Leakage Current	_		±100	nA	$V_{GE} = \pm 20V$	

## Switching Characteristics @ T<sub>J</sub> = 25°C (unless otherwise specified)

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	Parameter	Min.	Тур.	Max.	Units	Condition	าร	
$Q_g$	Total Gate Charge (turn-on)	_	25	30		$I_{\rm C} = 9.0 A$		
$Q_{ge}$	Gate - Emitter Charge (turn-on)	_	_	6.0	nC	$V_{CC} = 960V$		
$Q_{gc}$	Gate - Collector Charge (turn-on)	_		15				
t <sub>d(on)</sub>	Turn-On Delay Time	_	2.3	_		$T_J = 25^{\circ}C$		
t <sub>r</sub>	Rise Time	_	10	_	ns	$I_C = 9.0A, V_{CC} = 960V$		
t <sub>d(off)</sub>	Turn-Off Delay Time	_	200	450		$V_{GE}$ = 15V, $R_G$ = 23 $\Omega$		
t <sub>f</sub>	Fall Time	_	210	390		Energy losses include "tail" and		
Eon	Turn-On Switching Loss	_	_	_		diode reverse recovery	-	
E <sub>off</sub>	Turn-Off Switching Loss	_	_	_	mJ	-		
E <sub>ts</sub>	Total Switching Loss	_	4.0	7.0				
t <sub>sc</sub>	Short Circuit Withstand Time	10	_	_	μs	$V_{CC} = 720V, T_J = 125^{\circ}$	C	
						$V_{GE} = 15V$ , $R_G = 23\Omega$ ,	V <sub>CPK</sub> < 1000V	
t <sub>d(on)</sub>	Turn-On Delay Time	_	33	_		T <sub>J</sub> = 150°C,		
t <sub>r</sub>	Rise Time	_	20	_	ns	$I_C = 9.0A$ , $V_{CC} = 960V$		
t <sub>d(off)</sub>	Turn-Off Delay Time	_	480	_		$V_{GE} = 15V$ , $R_G = 23\Omega$		
t <sub>f</sub>	Fall Time	_	450	_		Energy losses include "tail" and		
E <sub>ts</sub>	Total Switching Loss	_	8.0	_	mJ	diode reverse recovery.		
LE	Internal Emitter Inductance	_	13	_	nΗ	Measured 5mm from package		
C <sub>ies</sub>	Input Capacitance	_	670	_		V <sub>GE</sub> = 0V		
C <sub>oes</sub>	Output Capacitance	_	50	_	pF	V <sub>CC</sub> = 30V		
C <sub>res</sub>	Reverse Transfer Capacitance	_	10	_		f = 1.0MHz		
t <sub>rr</sub>	Diode Reverse Recovery Time	_	53	80	ns	T <sub>J</sub> = 25°C		
		_	87	130		T <sub>J</sub> = 125°C	$I_F = 6.0A$	
I <sub>rr</sub>	Diode Peak Reverse Recovery Current	_	4.4	8.0	Α	T <sub>J</sub> = 25°C		
		_	5.0	9.0		T <sub>J</sub> = 125°C	$V_{R} = 200V$	
Q <sub>rr</sub>	Diode Reverse Recovery Charge	_	116	320	nC	T <sub>J</sub> = 25°C		
		_	233	585		T <sub>J</sub> = 125°C	di/dt = 200A/µs	
di <sub>(rec)M</sub> /dt	Diode Peak Rate of Fall of Recovery	_	180	_	A/µs	T <sub>J</sub> = 25°C	,	
	During t <sub>b</sub>	_	100	_		T <sub>J</sub> = 125°C		

Notes: ① Repetitive rating; V <sub>GE</sub>=20V, pulse width limited by max. junction temperature.

<sup>@</sup>  $V_{CC} = 80\% (V_{CES}),\ V_{GE} = 20V,\ L = 10 \mu H, \\ R_G = 23 \Omega$ 

Pulse width 5.0µs, single shot.

③ Pulse width  $\leq 80\mu s$ ; duty factor  $\leq 0.1\%$ .